

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Tai-Sheng Feng	11/19/2010
Le-Tien Jung	11/19/2010
RECEIVING PARTY DATA	
Name:	Taiwan Memory Company
Street Address:	No.180, Sec 2, Gongdao 5th Rd.
City:	Hsinchu City
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12980349
CORRESPONDENCE DATA	
Fax Number: (703)997-4517 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 3027291562 Email: Patent.admin.uspto.cr@naipo.com Correspondent Name: WINSTON HSU Address Line 1: P.O.BOX 506 Address Line 4: Merrifield, VIRGINIA 22116	
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NAME OF SUBMITTER:	JANINE CHANG
Total Attachments: 2 source=1019897#page1.tif source=1019897#page2.tif	

CH \$40.00 12980349

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PATENT
REEL: 025551 FRAME: 0387

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Tai-Sheng Feng Nationality: TW

Name: Le-Tien Jung Nationality: TW

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: Taiwan Memory Company

Address: No.180, Sec 2, Gongdao 5th Rd., Hsinchu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"MANUFACTURING METHOD FOR A BURIED CIRCUIT STRUCTURE"

Which is found in :

- (a) + U.S. patent application executed on even date
(b) _____ U.S. patent application executed on _____
(c) _____ U.S. application serial no. _____
(d) _____ patent no. _____ issued _____

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this _____ (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Tai-Sheng Feng

Le-Tien Jung

Signature of INVENTOR

Tai Sheng Feng NOV 19 2010
Le-Tien Jung 11/19/10